Combined Dynamic Voltage Scaling and Adaptive Body Biasing for Lower Power Microprocessors under Dynamic Workloads

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Abstract

Dynamic voltage scaling (DVS) reduces the power consumption of processors when peak performance is unnecessary. However, the achievable power savings by DVS alone is becoming limited as leakage power increases. In this paper, we show how the simultaneous use of adaptive body biasing (ABB) and DVS can be used to reduce power in high-performance processors. Analytical models of the leakage current, dynamic power, and frequency as functions of supply voltage and body bias are derived and verified with SPICE simulation. We then show how to determine the correct trade-off between supply voltage and body bias for a given clock frequency and duration of operation. The usefulness of our approach is evaluated on real workloads obtained using real-time monitoring of processor utilization for four applications. The results demonstrate that application of simultaneous DVS and ABB results in an average energy reduction of 48% over DVS alone.

1. Introduction

Power consumption has become an overriding constraint for microprocessor designs, not only in mobile environments, but in desktop and server applications as well. Traditionally, the priority has been on performance, and consequently, the supply voltage has been set at the maximum allowable level based on device breakdown potentials to enable fast operation. During typical use, however, applications may not require the maximum achievable performance. A number of methods have been proposed that take advantage of these substantial periods of low utilization by scaling the supply voltage and clock frequency, resulting in a reduction in dynamic power consumption [1-3].

While these dynamic voltage scaling (DVS) methods are effective in addressing the dynamic power consumption, they are significantly less effective in reducing the leakage power. As minimum feature sizes shrink, supply voltage scaling requires a reduction in the threshold voltage which results in an exponential increase in leakage current with each new technology generation. Even in today's technologies, it is not uncommon for leakage power to comprise as much as 20% of the total power consumption [4]. As technologies continue to scale, it is expected that leakage power will become comparable to dynamic power consumption [5]. Furthermore, the application of DVS results in reduced dynamic power consumption, thereby causing leakage power to dominate.

For processors operating under dynamic computational loads, it is therefore essential that both leakage and dynamic power are addressed effectively. Previously, adaptive reverse body biasing (ABB) has been proposed to control the leakage current during standby mode [6-8]. Recently, methods using forward body biasing have also been proposed [9,10]. Adaptive body biasing has the advantage that it reduces the leakage current exponentially, whereas dynamic voltage scaling reduces leakage current linearly. In this paper, we propose the use of simultaneous

dynamic voltage scaling and adaptive reverse body biasing to control both dynamic and leakage power.

The difficulty in employing simultaneous DVS and ABB is in determining the optimal trade-off between supply voltage and reverse body bias voltage such that the total power consumption at a particular operating frequency is minimized. The possible combinations of supply voltage and body bias are constrained by the requirement that circuit delays meet the specified clock frequency targets.

We derive an analytical expression for the optimal supply voltage and body bias for a given frequency and expected duration of operation and present analytical models that express the power consumption and processor performance as a function of the body and supply voltages. We also show how to fit these functions to SPICE simulation results with good accuracy (Section 2). By using the performance of the processor as a constraint, resulting two dimensional optimization task is reduced to a one dimensional task and is solved through differentiation (Section 3). The analytical expression for the optimal supply voltage and body bias was verified through SPICE simulations.

The proposed simultaneous DVS and ABB method was then applied to a processor and was compared with using DVS alone (Section 4). The dynamic processor loads were obtained through measurements on a 600MHz Crusoe processor for four different applications. Expected gains from using simultaneous DVS and ABB were evaluated at a current 0.18µm technology as well as for a projected 0.07µm technology. In Section 5 we draw our conclusions.

2. Power and Performance Models

We first derive the threshold voltage and power consumption as functions of the supply and bias voltages. We then derive the performance as a function of these voltages. In all cases, we compare the analytical model to SPICE simulation results.

2.1 Threshold Voltage

The threshold voltage of a short-channel MOSFET transistor in the BSIM model [11,12] is given by,

$$V_{th} = V_{th0} + \gamma (\sqrt{\Phi_s - V_{bs}} - \sqrt{\Phi_s}) - \theta_{DIBL} V_{dd} + \Delta V_{NW}$$
 (1)

where V_{th0} is the zero-bias threshold voltage, Φ_s , γ , and θ_{DIBL} are constants for a given technology, V_{bs} is the voltage applied between the body and source of the transistor, ΔV_{NW} is a constant that models narrow width effects, and V_{dd} is the supply voltage. (1) shows that V_{th} has a linear dependence with V_{dd} . Furthermore, if $|V_{bs}| \approx \Phi_s$ then $\sqrt{\Phi_s - V_{bs}} - \sqrt{\Phi_s}$ can be linearized as $k \cdot V_{bs}$ which yields,

$$V_{th} = V_{th1} - K_1 \cdot V_{dd} - K_2 \cdot V_{bs} \tag{2}$$

where K_1 , K_2 , and V_{th1} are constants. Fig. 1 shows the linear dependence of V_{th} versus V_{dd} and V_{bs} as given by SPICE simulation of the Berkeley predictive models for a 0.07 μ m process [13]. A least squares method linear regression of V_{th} vs. V_{dd} and V_{bs} matches with (2) with an R^2 value of 0.997.

2.2 Power Consumption

The power consumed in a processor is the sum of dynamic, static, and short circuit power. The short circuit power consumption occurs only during signal transitions and is negligible [14]. The dynamic power, P_{AC} , is given by,

$$P_{AC} = C_{eff} V_{dd}^2 f (3)$$

where $C_{\rm eff}$ is the average switched capacitance per cycle, and f is the clock frequency. The major components of static current in a standard inverter are due to subthreshold conduction [15,16]. However, as [7,17] point out, the contributions of reverse bias junction current can be significant. Thus, the static power consumption, P_{DC} , is given by,

$$P_{DC} \approx V_{dd} I_{subn} + |V_{bs}| (I_{jn} + I_{bn}) \tag{4}$$

where I_{subn} is the subthreshold leakage current, and I_{jn} and I_{bn} are the drain and source to body junction leakage currents in the NMOS device. Transistor subthreshold leakage is modeled by,

$$I_{subn} = \left(\frac{W}{L}\right)I_{S}\left[1 - e^{\frac{-V_{dd}}{V_{T}}}\right]e^{\frac{-(V_{th} + V_{off})}{n V_{T}}}$$
(5)

where W and L are the device geometries, I_s , n, and V_{off} are empirically determined constants for a given process, and V_T is the thermal voltage [11]. V_{off} is typically small and $1 - \exp(-V_{dd}/V_T)$ is nearly 1 for all V_{dd} . This approximation and the substitution of (2) into (5) yields,

$$I_{subn} = K_3 e^{K_4 V_{dd}} e^{K_5 V_{bs}}$$
(6)

where K_3 - K_5 are constant fitting parameters. As $|V_{bs}|$ is increased, the current due to junction leakage, I_j , increases and counteracts the savings achieved by lowering I_{subn} . The maximum value of $|V_{bs}|$ before junction leakage overrides subthreshold current reduction is dependent on process and has been shown to vary from as high as -0.6V to -2.5V [8,18]. This crossover point is also highly dependent on temperature, where at higher operating temperatures, transistors exhibit a larger reduction in I_{subn} (and thus tolerate a larger $|V_{bs}|$) before I_j increases [8]. SPICE simulations for the 0.07µm process show that the crossover point is about -1.2V. Therefore, to be conservative, V_{bs} was constrained between 0 and -1V although in a different process, a lower cutoff point might be achievable. I_j can be approximated as a constant and the total static current, I_{stat} , becomes,

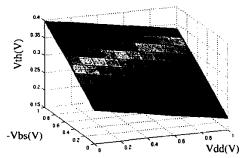


Fig. 1. V_{th} vs. both V_{dd} and V_{bs} as generated by SPICE simulation for a deep-submicron process.

$$I_{stat} = K_3 e^{K_4 V_{dd}} e^{K_5 V_{bs}} + I_i$$
(7)

Fig. 2 is a SPICE generated plot of I_{stat} vs. simultaneous changes in V_{dd} and V_{bs} . A comparison between I_{stat} as generated by SPICE and I_{stat} as generated by (7) yields an average error of 2.09% and a maximum error of only 5.63% for 0.3 < V_{dd} < 1V and -1 < V_{bs} < 0V. Substitution of (6) and (7) into (4) yields,

$$P_{DC} = V_{dd} K_3 e^{K_4 V_{dd}} e^{K_5 V_{bs}} + |V_{bs}| I_i$$
 (8)

and the total power consumption, P, becomes,

$$P = C_{eff} V_{dd}^{2} f + V_{dd} K_{3} e^{K_{4} V_{dd}} e^{K_{5} V_{bs}} + |V_{bs}| I_{i}$$
 (9)

2.3 Delay

The delay of a gate is a function of both the power supply and the threshold voltage of the internal transistors. Since the delay of complex gates remains proportional to the delay of standard inverter, the path delay can be modeled similarly to the alpha-power model of an inverter [19,20] as,

$$t_{inv} = \frac{L_d K_6}{\left(V_{dd} - V_{th}\right)^{\alpha}} \tag{10}$$

where L_d is the logic depth of the path [15], K_6 is a constant for γ given process technology, and α is a measure of velocity saturation. (10) differs from the standard alpha-power model to better fit SPICE simulation results when an α =1 is used. Substitution of (2) into (10) yields,

$$f = (L_d K_6)^{-1} ((1 + K_1) V_{dd} + K_2 V_{bs} - V_{th1})^{\alpha}$$
 (11)

Fig. 3 shows the plot of delay vs. V_{dd} and V_{bs} as determined using SPICE. A comparison between the SPICE data and the operating frequencies calculated using (11) yields an average percent error of 9.8% and a maximum percent error of 33.2% for $0.5 < V_{dd} < 1V$, $-1 < V_{bs} < 0V$, and $\alpha = 1$. While this maximum percent error is large, (11) produces worst-case frequencies which guarantee that the circuit will meet timing. The optimal power consumption, however, is not fully realized. V_{dd} scaling was limited to 0.5V since the V_{th} of a transistor approaches 0.38V when scaling.

3. Optimization

Now that the necessary models have been developed, the technique for finding optimal settings for implementing both DVS and ABB is presented. With three possible variables to control, V_{dd} , V_{bs} , and f, the optimization first begins with limiting the number of free variables.

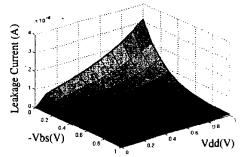


Fig. 2. Leakage current through an NMOS device vs. V_{dd} and $-V_{bs}$ as generated by SPICE simulation.

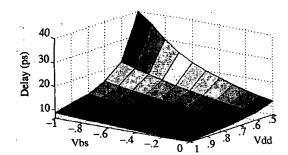


Fig. 3. Circuit delay vs. V_{dd} and V_{bs} as generated by SPICE.

3.1 Variable Reduction

The processor's algorithm for determining utilization based on workload generates a value for the required frequency eliminating one free variable. In order to eliminate a second variable, this frequency is treated as a constant for a given optimization point and (11) can be solved to find V_{dd} as a function of V_{bs} . In fact, if α =1, as modeled above, then (11) becomes,

$$V_{dd} = (L_d K_6 f - K_2 V_{bs} + V_{th1}) / (1 + K_1)$$

$$= \begin{cases} K_7 V_{bs} + K_{f1} & \text{if } V_{dd} > 0.5 \\ 0.5 & \text{otherwise} \end{cases}$$
(12)

where, for a given frequency,

$$K_7 = -K_2/(1+K_1), \quad K_{f1} = (V_{th1} + L_d K_7 f)/(1+K_1)$$
 (13)

3.2 Energy Minimization

The energy consumed per cycle is defined as power times cycle duration. By applying (9), the total energy consumed per cycle, $E_{\rm cyc}$, for an entire circuit is given by,

$$E_{cyc} = C_{eff} V_{dd}^{2} + L_{ef}^{-1} (V_{dd} K_{3} e^{K_{4} V_{dd}} e^{K_{5} V_{bs}} + |V_{bs}| I_{i})$$
 (14)

where $L_{\rm g}$ is the number of logic gates in the circuit. Unfortunately, there is also energy required in switching the circuit between varying power modes. This switching energy, $E_{\rm s}$, is given by,

$$E_s = \left| \Delta V_{dd} \right|^2 C_r + \left| \Delta V_{bs} \right|^2 C_s \tag{15}$$

where ΔV_{dd} is the change in V_{dd} , ΔV_{bs} is the change in V_{bs} , C_r is the capacitance of the power rail, and C_s is the total capacitance of the substrate and wells of the device. Let t be the duration of time in a given power mode then the total energy consumed in a particular mode is given by,

$$E_{tot} = E_s + t \cdot f \cdot E_{cyc} \tag{16}$$

Differentiating (16) with respect to V_{hs} yields,

$$\frac{\partial E_{tot}}{\partial V_{bs}} = \frac{\partial E_s}{\partial V_{bs}} + (t \cdot f) \frac{\partial E_{cyc}}{\partial V_{bs}}$$
 (17)

where by substituting in (12).

$$\frac{\partial E_s}{\partial V_{bs}} = \begin{cases} 2(K_7^2 C_r + C_s) V_{bs} + 2C_r K_7 (K_{f1} + V_{dd0}) \\ -2C_s V_{bs0} & \text{if } V_{dd} > 0.5 \\ -2C_s (V_{bs0} - V_{bs}) & \text{otherwise} \end{cases}$$
(18)

and

| Variable | Value | Variable | Value | Variable | Value |
|----------------|-----------------------|----------------|------------------------|---------------|------------------------|
| K_l | 0.063 | K ₆ | 5.26x10 ⁻¹² | V_{thl} | 0.244 |
| K ₂ | 0.153 | K ₇ | -0.144 | I_j | 4.80x10 ⁻¹⁰ |
| K ₃ | 5.38x10 ⁻⁷ | t | 5x10 ⁻⁵ | Ceff | 2.00x10 ⁻¹⁵ |
| K ₄ | 1.83 | V_{dd0} | 1 | $L_{d_i} L_g$ | 10 |
| K ₅ | 4.19 | V_{bs0} | 0 | Cr | 1x10 ⁻¹² |
| Max f | 15.6 GHz | C_s | 1x10 ⁻¹² | | |

TABLE 1. Constants for a 0.07μm, 10 inverter chain.

$$\frac{\partial E_{cyc}}{\partial V_{bs}} = \begin{cases} L_g K_3 f^{-1} (k_1 V_{bs} + k_2) e^{k_3 V_{bs} + k_4} - I_j L_g f^{-1} \\ + 2 C_{eff} (k_5 V_{bs} + k_6) & \text{if } V_{dd} > 0.5 \\ \frac{L_g}{2f} (K_3 K_5 e^{K_5 V_{bs} + 0.5 K_4} - 2I_j) & \text{otherwise} \end{cases}$$
(19)

In (19), k_I - k_6 are constants derived from the other process variables, K_I - K_7 . Their values for a 10 inverter chain are presented in Table 1. Fig. 4 shows the derivative of total energy vs. V_{bs} . The zero crossing indicates the V_{bs} for minimum energy consumption. Fig. 5 shows the required V_{bs} and V_{dd} for minimum energy consumption at a given frequency. For any $t > 50 \mu s$, the V_{dd} and V_{bs} values are independent of t while for $t < 50 \mu s$, V_{dd} and V_{bs} scale with duration. The shorter duration cycles do not lend themselves to large voltage changes because the energy required to switch V_{dd} and V_{bs} can not be amortized over as many cycles as during the longer duration cycles. Fig. 6 shows the energy savings achievable by using both DVS and ABB. The average energy reduction over all frequencies by simultaneous DVS and ABB as opposed to just DVS is 54% while the savings over a circuit with no scaling is 74%. SPICE simulated values for total energy and the expected values based on (16) agree with an average error of 12.7% and a maximum error of 28.8%.

4. Microprocessor Results

The proposed method of simultaneous DVS and ABB was applied to a mobile processor using the derived optimal trade-off between supply voltage and body-bias. The dynamic processor load was obtained through hardware monitoring as explained in the following section. The application of the simultaneous DVS and ABB method and the resulting energy savings are discussed in Sections 4.2 and 4.3.

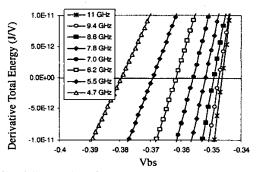


Fig. 4. Derivative of total energy w.r.t. V_{bs} vs. V_{bs} . Zero crossing shows the V_{bs} value that produces minimum energy consumption for a given frequency.

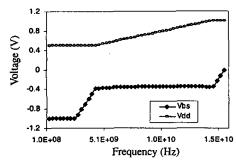


Fig. 5. Plot of the V_{dd} and V_{bs} values for optimal energy reduction in a 50 μ s duration low-power state.

4.1 Workload

Performance-setting algorithms dynamically adjust the processor's performance level while ensuring that the software running on the processor meets its deadlines. For some applications, there is a very clear notion of what these deadlines are. During video playback, for example, the performance-setting algorithm must ensure that the desired framerate (usually 30 frames/second) is achieved. Setting the performance too low would cause the application to have jerkier playback while decoding a frame too quickly unnecessarily increases power consumption since finishing a task before its deadline implies that the performance level was set too high. The goal of the performance-setting strategy is to stretch the execution of each task exactly to its deadline and scale the supply voltage and body bias voltage to their optimal values for the required performance. The only difficulty is in knowing exactly what the deadlines are. Our algorithm is implemented in the Linux kernel and relies on monitoring system calls and inter-task communication to derive deadlines automatically and without modification of user programs [2]. Unlike many similar algorithms, ours is equally effective for interactive and realtime (periodic) workloads.

The traces for this paper were collected on a Sony Picture-book PCG-C1VN which uses the Transmeta Crusoe 5600 processor whose performance level can be varied between 300 - 600MHz in 100MHz steps (or frequency scaled between 50 - 100% in 16% steps). While this processor has its own algorithm for controlling the processor performance levels, we have over-ridden it with our own performance-setting algorithm. During the benchmark runs, the processor's frequency was varied between 300MHz and 600MHz and the measured performance levels were used to compute the expected energy using either DVS alone or using simultaneous DVS and ABB. Moreover, we noticed that for many of our benchmarks, even the minimum speed of this processor was unnecessarily fast. Some of our applications would meet their deadlines with a performance level of 10% of peak. Therefore, we also estimated the effects on energy

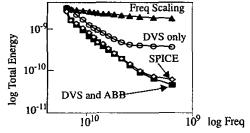


Fig. 6. Total energy consumed by 10 inverters using low power scaling techniques for a 10ms time period.

consumption for a conceptual processor that could run over a wider range of frequency values. The frequency values ranged from 10-100% in 5% steps. We compare these energy results with those from the more restricted range where the minimum frequency was restricted to 50% of maximum performance. The four benchmarks in this paper are:

- xmms-mp3: mp3 audio playback with xmms player (See Fig. 7).
- · mpeg: video playback of Red's Nightmare.
- · emacs: record of an editing session in emacs.
- os: miscellaneous UNIX operations (e.g. grep, ls, vi, awk, perl, etc.).

4.2 Optimization

sor were calculated using published data on the processor [21]. The fitting parameters (Table 2) were adapted from the Berkeley predicted models for a 0.18 µm process [13]. It is recognized that as technology continues to scale, processes incur higher leakage [22]. In fact, the static power in current 0.18 µm high-performance processors comprises 20% of total power [4]. Conservatively, our 0.18µm simulations have only 10% leakage power. To forecast for future generations, constant values were also calculated for the higher-leakage 0.07 µm predicted process. The 0.07µm process's leakage power is 30% of dynamic power. To ensure a fair comparison, both the 0.18 µm and 0.07 µm processes had the ability to scale V_{dd} and V_{bs} equally. The minimum duration at any utilization was set at 200 μ s which is a conservative estimate of V_{dd} and V_{bs} switching times based on previous published data [6]. During these switching periods, the higher-power state was used as an estimate of total energy. Fig. 7 shows a section of the trace for the xmms-mp3 player and the required V_{dd} and V_{hs} values for energy optimization in the 0.07 μ m technology.

4.3 Energy Savings

Table 3 shows the energy reduction achieved by employing both DVS and ABB in the 0.18 μ m process using scaling between 50-100% in 16% steps. The average energy savings over DVS only schemes is 23%. The more aggressive performance scaling (10-100% scaling) does not yield further benefits in the 0.18 μ m process because the longer run times during active cycles overide the benefits achieved during the idle states when the clock is halted and only static power is consumed. This is due to the relatively low-leakage nature of the 0.18 μ m process.

Table 4 shows the energy reduction achieved by simultaneous DVS and ABB scaling in the 0.07µm process. The performance scaling between 50-100% of peak shows an average energy reduction of 39% over DVS alone while the scaling between 10-100% of peak has an average energy reduction of 48%. The most benefit is achieved in applications like emacs where the processor spends a lot of time idling and consumes mostly static power which is reduced by the body biasing.

| Variable | Value | Variable | Value | Variable | Value |
|----------------|----------------------|------------------|----------------------|-----------|------------------------|
| K_{I} | 0.053 | K ₆ | 51x10 ⁻¹² | V_{thI} | 0.359 |
| K ₂ | 0.140 | K ₇ | -0.132 | l_j | 2.40x10 ⁻¹⁰ |
| K ₃ | 3.0x10 ⁻⁹ | t | 5x10 ⁻⁵ | C_{eff} | 1.11x10 ⁻⁹ |
| K ₄ | 1.63 | V _{dd0} | 1.6 | L_d | 37 |
| K ₅ | 3.65 | V _{bsO} | o | C_r | 1x10 ⁻⁶ |
| Max f | 600 MHz | C_s | 4x10 ⁻⁶ | L_{g} | 4x10 ⁶ |

TABLE 2. Constants for the Crusoe 5600 processor in the 0.18 m process.

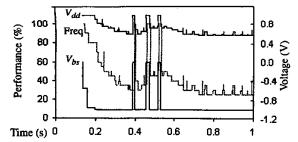


Fig. 7. Subset of the trace for the xmms-mp3 player showing performance and optimal V_{dd} and V_{hs} .

5. Conclusion

We examined an energy reduction technique through simultaneous implementation of DVS and ABB and presented an analytical expression for power consumption and processor performance as functions of three control parameters (frequency, supply voltage, and body bias voltage). A closed-form method for finding the proper V_{dd} and V_{bs} for optimal power consumption was also presented. Furthermore, this optimal solution was easily obtained using process parameters from SPICE simulation and design specifications. The optimal parameters were applied to both actual and simulated workloads for a 600MHz, 0.18µm mobile processor. The results show that the simultaneous implementation of DVS and ABB power scaling techniques produce an average energy reduction of 23% in a 0.18µm process and 39% in a predicted 0.07µm process over DVS alone when scaling performance between 50 - 100%. Energy reductions of nearly 50% were achieved through more aggressive performance scaling (10 - 100%) in the 0.07µm process. The results also suggest that as technology scales and leakage power increases, simultaneous DVS and ABB scaling will become more effective.

Acknowledgements

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| 0.18µm Process | xmms-mp3 | mpeg | emacs | os |
|--------------------------------------|----------|-------|-------|-------|
| No scaling | 23 J | 47 J | 13 J | 37 J |
| DVS alone (reduction vs. no scaling) | 9.4 J | 21 J | 4.7 J | 18 J |
| | (60%) | (55%) | (63%) | (51%) |
| DVS & ABB (reduc- | 7.6 J | 19 J | 2.8 J | 14 J |
| tion vs. DVS alone) | (19%) | (10%) | (40%) | (21%) |

TABLE 3. Energy consumed and percent reduction in the 0.18µm technology under several workloads with frequency scaling between 50-100% with 16% steps.

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| 0.07μm Process | Freq. scaling between 50-100% in 16% steps | | | | Freq. scaling between 10-100% in 5% steps | | | |
|-------------------------------------|--|-----------|------------|-----------|---|-----------|------------|-----------|
| | xmms-mp3 | mpeg | emacs | os | xmms-mp3 | mpeg | emacs | os |
| No scaling | 65J | 111J | 50J | 119J | 65J | 111J | 50J | 1193 |
| DVS alone (reduction vs.no scaling) | 26J (60%) | 47J (57%) | 18J (64%) | 53J (55%) | 15J (76%) | 42J (62%) | 11J (78%) | 37J (70%) |
| DVS & ABB (reduction vs. DVS) | 16J (38%) | 36J (22%) | 9.3J (48%) | 34J (35%) | 8.4J (45%) | 32 (22%) | 2.1J (80%) | 19J (47%) |

TABLE 4. Energy consumed and percent reduction for DVS only, and DVS and ABB under two frequency scaling regimes.